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ZVP4525Z

250V P-CHANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS} = -250V$; $R_{DS(ON)} = 14\Omega$; $I_D = -205mA$

DESCRIPTION

This 250V enhancement mode P-channel MOSFET provides users with a competitive specification offering efficient power handling capability, high impedance and is free from thermal runaway and thermally induced secondary breakdown. Applications benefiting from this device include a variety of Telecom and general high voltage switching circuits.

SOT223 and SOT23-6 versions are also available.

FEATURES

- High voltage
- Low on-resistance
- Fast switching speed
- Low gate drive
- Low threshold
- Complementary N-channel Type ZVN4525Z
- SOT89 package

APPLICATIONS

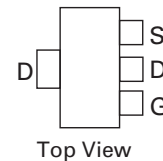
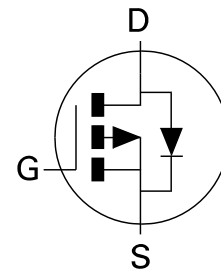
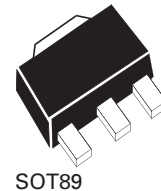
- Earth Recall and dialling switches
- Electronic hook switches
- High Voltage Power MOSFET Drivers
- Telecom call routers
- Solid state relays

ORDERING INFORMATION

DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZVP4525ZTA	7	12mm embossed	1000 units
ZVP4525ZTC	13	12mm embossed	4000 units

DEVICE MARKING

- P52



ZVP4525Z

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DSS}	250	V
Gate Source Voltage	V _{GS}	±40	V
Continuous Drain Current (V _{GS} =10V; T _A =25°C)(a) (V _{GS} =10V; T _A =70°C)(a)	I _D I _D	-205 -164	mA mA
Pulsed Drain Current (c)	I _{DM}	-1	A
Continuous Source Current (Body Diode)	I _S	-0.75	A
Pulsed Source Current (Body Diode)	I _{SM}	-1	A
Power Dissipation at T _A =25°C (a) Linear Derating Factor	P _D	1.2 9.6	W mW/°C
Operating and Storage Temperature Range	T _j ; T _{stg}	-55 to +150	°C

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	R _{θJA}	103	°C/W
Junction to Ambient (b)	R _{θJA}	50	°C/W

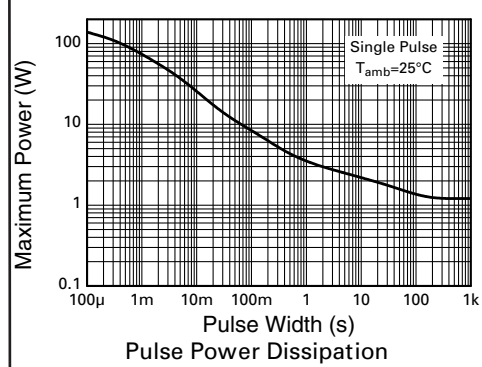
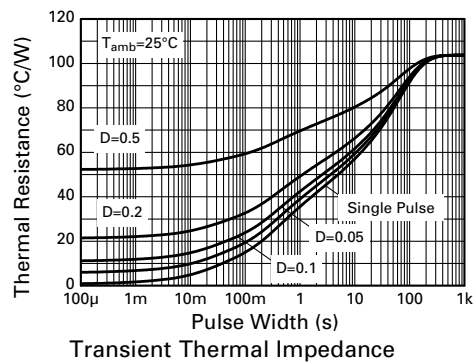
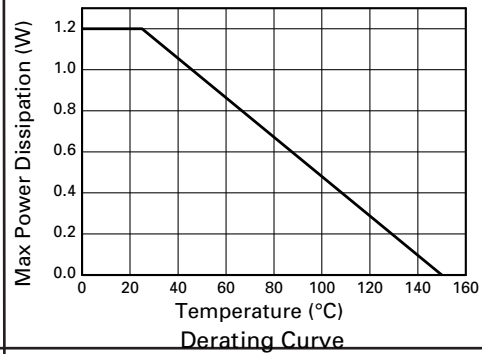
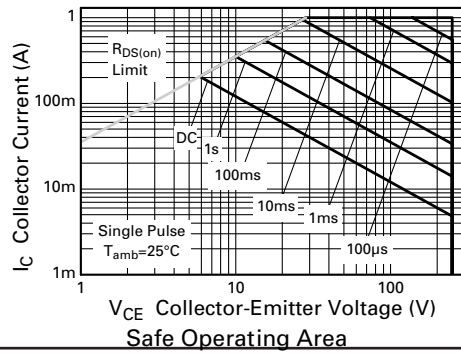
NOTES

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
(b) For a device surface mounted on FR4 PCB measured at t ≤ 5 secs.
(c) Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.

NB High Voltage Applications

For high voltage applications, the appropriate industry sector guidelines should be considered with regard to voltage spacing between conductors.

CHARACTERISTICS



ZVP4525Z

ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

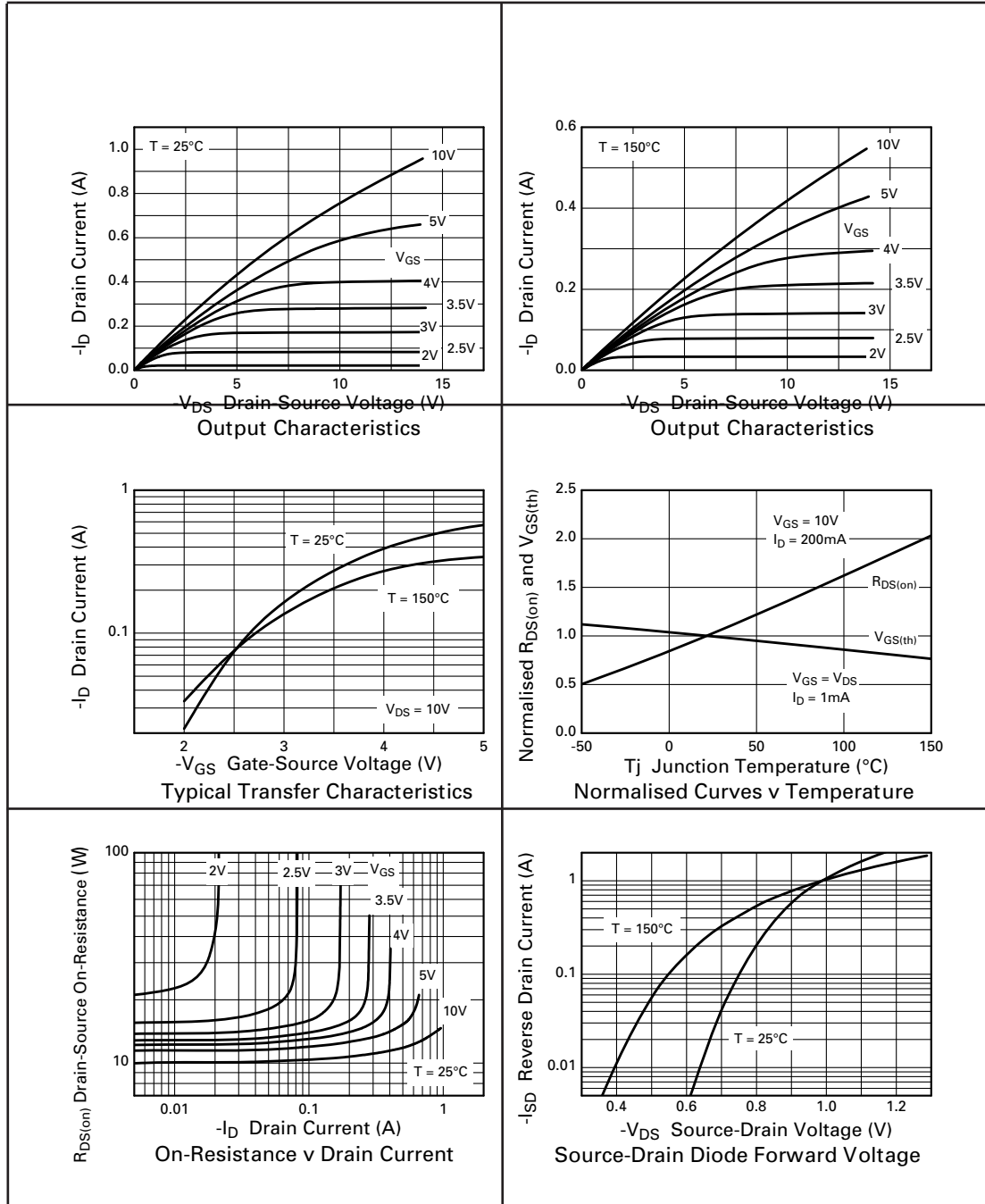
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS.
STATIC						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	-250	-285		V	I _D =-1mA, V _{GS} =0V
Zero Gate Voltage Drain Current	I _{DSS}		-30	-500	nA	V _{DS} =-250V, V _{GS} =0V
Gate-Body Leakage	I _{GSS}		±1	±100	nA	V _{GS} =±40V, V _{DS} =0V
Gate-Source Threshold Voltage	V _{GS(th)}	-0.8	-1.5	-2.0	V	I _D =-1mA, V _{DS} = V _{GS}
Static Drain-Source On-State Resistance (1)	R _{DS(on)}		10 13	14 18	Ω Ω	V _{GS} =-10V, I _D =-200mA V _{GS} =-3.5V, I _D =-100mA
Forward Transconductance (3)	g _{fs}	80	200		mS	V _{DS} =-10V,I _D =-0.15A
DYNAMIC (3)						
Input Capacitance	C _{iss}		73		pF	V _{DS} =-25 V, V _{GS} =0V, f=1MHz
Output Capacitance	C _{OSS}		12.8		pF	
Reverse Transfer Capacitance	C _{rss}		3.91		pF	
SWITCHING(2) (3)						
Turn-On Delay Time	t _{d(on)}		1.53		ns	V _{DD} =-30V, I _D =-200m A R _G =50Ω, V _{GS} =-10V (refer to test circuit)
Rise Time	t _r		3.78		ns	
Turn-Off Delay Time	t _{d(off)}		17.5		ns	
Fall Time	t _f		7.85		ns	
Total Gate Charge	Q _g		2.45	3.45	nC	V _{DS} =-25V,V _{GS} =-10V, I _D =-200mA(refer to test circuit)
Gate-Source Charge	Q _{gs}		0.22	0.31	nC	
Gate Drain Charge	Q _{gd}		0.45	0.63	nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V _{SD}			0.97	V	T _j =25°C, I _S =-200mA, V _{GS} =0V
Reverse Recovery Time (3)	t _{rr}		205	290	ns	T _j =25°C, I _F =-200mA, di/dt=100A/μs
Reverse Recovery Charge (3)	Q _{rr}		21	29	nC	

(1) Measured under pulsed conditions. Width=300 μs . Duty cycle $\leq 2\%$.

(2) Switching characteristics are independent of operating junction temperature.

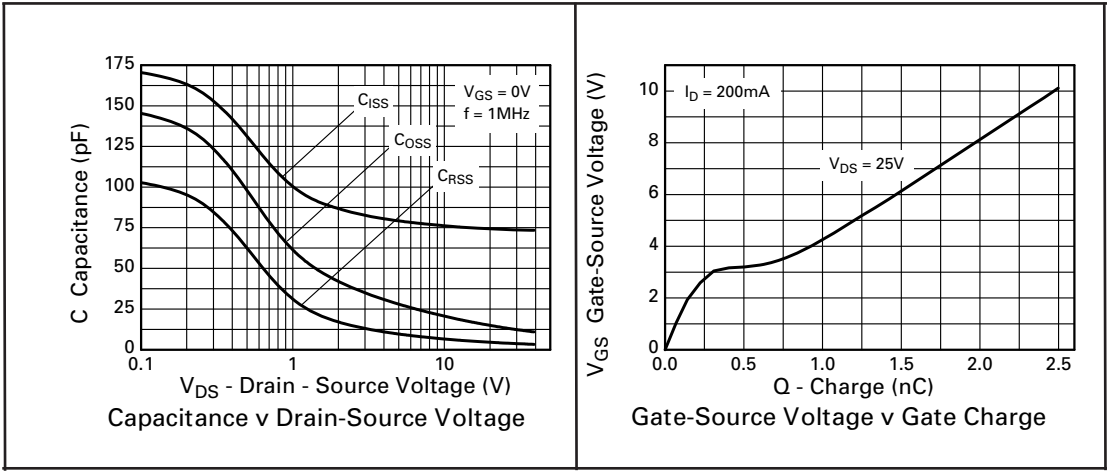
(3) For design aid only, not subject to production testing.

TYPICAL CHARACTERISTICS



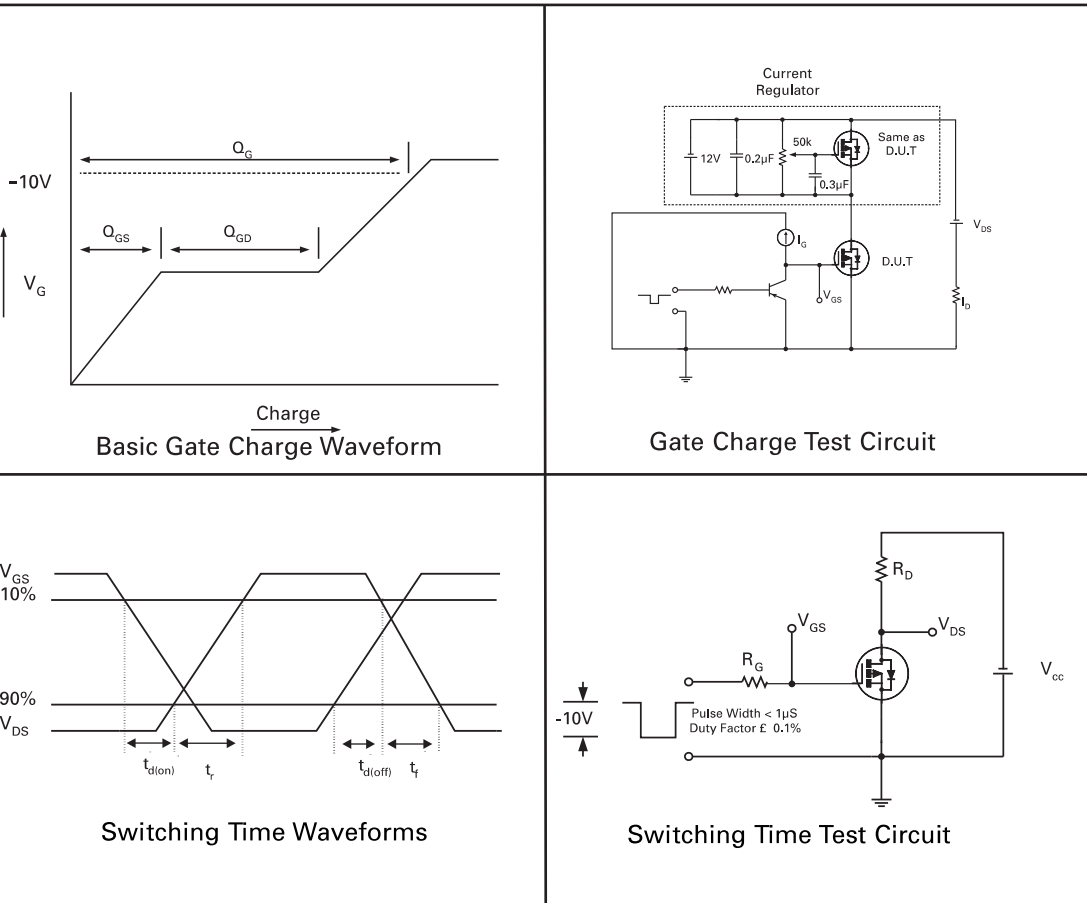
ZVP4525Z

CHARACTERISTICS



TEST CIRCUITS

ZVP4525Z



ZVP4525Z

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"Preview"Future device intended for production at some point. Samples may be available

"Active"Product status recommended for new designs

"Last time buy (LTB)"Device will be discontinued and last time buy period and delivery is in effect

"Not recommended for new designs"Device is still in production to support existing designs and production

"Obsolete"Production has been discontinued

Datasheet status key:

"Draft version"This term denotes a very early datasheet version and contains highly provisional information, which may change in any manner without notice.

"Provisional version"This term denotes a pre-release datasheet. It provides a clear indication of anticipated performance. However, changes to the test conditions and specifications may occur, at any time and without notice.

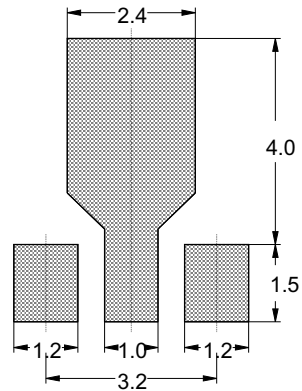
"Issue"This term denotes an issued datasheet containing finalized specifications. However, changes to specifications may occur, at any time and without notice.

ZVP4525Z

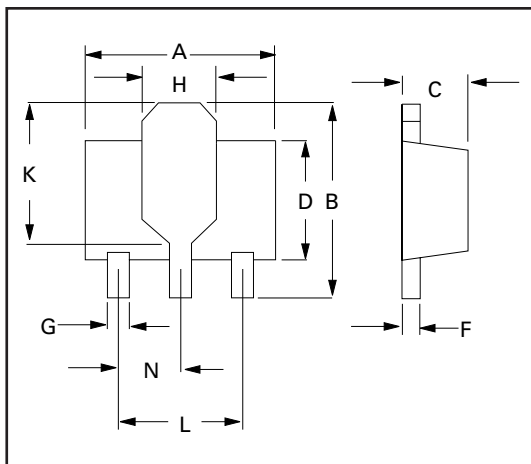
PACKAGE DIMENSIONS

DIM	Millimetres		Inches	
	Min	Max	Min	Max
A	4.40	4.60	0.173	0.181
B	3.75	4.25	0.150	0.167
C	1.40	1.60	0.550	0.630
D	-	2.60	-	0.102
F	0.28	0.45	0.011	0.018
G	0.38	0.55	0.015	0.022
H	1.50	1.80	0.060	0.072
K	2.60	2.85	0.102	0.112
L	2.90	3.10	0.114	0.122
N	1.40	1.60	0.055	0.063

PAD LAYOUT DETAILS



SOT89 pattern.
Minimum Pad Size (dimensions in mm)



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